HEUCOPHOS® ZPO

in Silicone resin

Solvent based coatings | Evonik Tego formulation No. AC 900 9 002 | Rev. Number: 01.01 | 10/20

Function	Product	Producer	PBW
Methyl phenyl silicone resin	SILIKOPHEN® AC 900	Evonik	40.50
Solvent	Xylene		13.00
Wetting and dispersing agent	TEGO® Dispers 628	Evonik	2.00
Substrate wetting agent	TEGO® Wet 270	Evonik	0.10
Rheology modifier	BENTONE® SD-1	Elementis	1.50
Muscovite mica	MICA TM	Aspanger	16.00
Anticorrosive pigment	HEUCOPHOS® ZPO	Sudarshan	5.00
Copper chromite black spinel	HEUCODUR® Black 9-100	Sudarshan	8.00
Rheology modifier	AEROSIL® R 972	Evonik	1.50
Grind with a bead mill.			
Solvent	Butyl glycol acetate		2.10
Solvent	Xylene		10.30
Add while stirring.			
			100.00

Specifications	
Vol.-% Anticorrosive pigment reg. pigment/filler	13.5
PVC in %	24.8
Solids in %	70.0

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